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Art Unit: 2811

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IN THE CLAIMS:

Please cancel claims 9 and 10 without prejudice or disclaimer, amend claims 1 and 18-19,
and add new claims 20-23 shown in the attached sheet(s).

REPLACEMENT CLAIMS

Please amend the claims by substituting the following claims for the pending claims with the same number and adding new claims as indicated.

1. (Twice Amended) A method of making a semiconductor device, the method comprising the steps of:
- mounting a semiconductor chip on a lower conductor, with first solder material applied between the chip and the lower conductor;
 - positioning an upper conductor on the chip, with second solder material applied between the chip and the upper conductor;
 - heating up the first and the second solder materials beyond melting points of the respective materials; and
 - solidifying the first and the second solder materials;
 - wherein the lower conductor includes a die pad portion for mounting the semiconductor chip; and
 - wherein the first solder material is caused to solidify earlier than the second solder material in the solidifying step for securing the semiconductor chip on the die pad portion of the lower conductor before the upper conductor is fixedly connected to the semiconductor chip.
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9. Deleted

10. Deleted

18. (Amended) The method according to claim 17, wherein the lower conductor further comprises lower lead portions extending from the die pad portion.

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19. (Amended) The method according to claim 18, wherein the second conductive pattern comprises upper lead portions at least one of which is to be connected to the semiconductor chip as the upper conductor.

20. (New) The method according to claim 19, further comprising the step of removing at least one of the lower and the upper lead portions from the frame.

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21. (New) The method according to claim 19, wherein the frame comprises first and second common bars parallel to each other, the upper lead portions being divided into first and second groups, the upper lead portions in the first group extending from the first common bar toward the second common bar, the upper lead portions in the second group extending from the second common bar toward the first common bar.

22. (New) A method of making a semiconductor device, the method comprising the steps of:

mounting a semiconductor chip on a lower conductor, with first solder material applied between the chip and the lower conductor;

positioning an upper conductor on the chip, with second solder material applied between the chip and the upper conductor;

heating up the first and the second solder materials beyond melting points of the respective materials; and

solidifying the first and the second solder materials;

wherein the first solder material is caused to solidify earlier than the second solder material in the solidifying step; and

wherein the heating of the first solder material is terminated earlier than the heating of the second solder material.

23. (New) A method of making a semiconductor device, the method comprising the steps of:

mounting a semiconductor chip on a lower conductor, with first solder material applied between the chip and the lower conductor;

positioning an upper conductor on the chip, with second solder material applied between the chip and the upper conductor;

heating up the first and the second solder materials beyond melting points of the respective materials; and

solidifying the first and the second solder materials;

wherein the first solder material is caused to solidify earlier than the second solder material in the solidifying step; and

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wherein the heating of the first and the second solder materials is performed by
contacting the lower and the upper conductors with first and second heaters, respectively.
